



## 26<sup>th</sup> IEEE International SoC Conference (SOCC)

September 04 – 06, 2013

Fraunhofer Institute for Integrated Circuits (IIS),  
Erlangen (near Nuremberg), Germany



### CALL FOR PAPERS

<http://www.ieee-socc.org>



The SOCC Conference is a premier forum for sharing advances in SoC technologies and applications in the areas of digital systems, circuit architectures, design methods, tools, automation, manufacturing, test, and emerging technologies. The 26<sup>th</sup> SOCC will be held at Fraunhofer IIS in Erlangen, Germany and will offer three days of technical papers, technical workshops, a vendor exhibition and a “IIS-lab-tour”. For updates and travel advice please check our website regularly <http://www.ieee-socc.org> or follow us on twitter “@ieee\_socc” (or [http://twitter.com/ieee\\_socc](http://twitter.com/ieee_socc)).  
**contact :** [info@ieee-socc.org](mailto:info@ieee-socc.org)

### SUBMISSION OF PAPERS AND WORKSHOP/TUTORIAL PROPOSALS

Electronic paper submissions are in *pdf* format, limited to **six** double-column IEEE format pages. The SOCC proceedings will be published on **IEEE Xplore**<sup>®</sup>. Embedded tutorial proposals with title, a half-page summary, and speaker's short bio are submitted to the Tutorial Chair

### SOCC TECHNICAL SCOPE

Papers are invited which address new and previously unpublished results in the areas:

- Analog and Mixed-Signal Circuits and Systems
- Biomedical Circuits and Systems
- Wireline and Wireless Communication Circuits and Systems
- Digital Signal Processing (DSP) Circuits and Systems
- Low-Power, Green Circuits, Systems, and Design Methodologies
- Embedded Systems, Multi/Many Core Systems and Embedded Memory Technologies
- Network on Chip (NoC), Interconnects, and 3D-IC
- Reconfigurable and Programmable Circuits and Systems
- System Level Design Methodology and tools
- Design for Testability and Manufacturability
- Design Verification
- MEMS and Emerging Technologies

### IMPORTANT DATES

Abstract and tutorial proposal submission deadline:	April 8th, 2013
Paper submission deadline:	April 15th, 2013
Notification of acceptance:	June 10th, 2013
Final camera-ready paper due:	June 24th, 2013

### ORGANIZING COMMITTEE

Conference General Chair: *Norbert Schuhmann, Fraunhofer IIS*  
Technical Program Chair: *Kaijian Shi, Cadence Design Systems*  
Technical Program Co-Chair: *Nagi Naganathan, LSI Corp*  
Tutorial Chair: *Yuejian Wu, Infineon*

Steering Committee Chair: *Ramalingam Sridhar, SUNY at Buffalo*  
Europe Liaison: *Sakir Sezer, Queen's Univ. Belfast*  
Asia Liaison: *Sao-Jie Chen, National Taiwan University*  
Industry Liaison: *Andrew Marshall*